

HSB276AYP

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0595-0100 (Previous: ADE-208-1051) Rev.1.00 Apr 06,2005

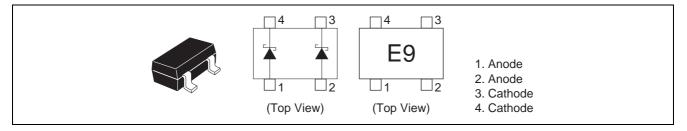
Features

- High forward current, Low capacitance.
- CMPAK-4 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB276AYP	E9	CMPAK-4	PTSP0004ZB-A (CMPAK-4)

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Repetitive peak reverse voltage	V _{RRM}	5	V
Reverse voltage	V _R	3	V
Average rectified current	I ₀ * ¹	30	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. Per one device.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

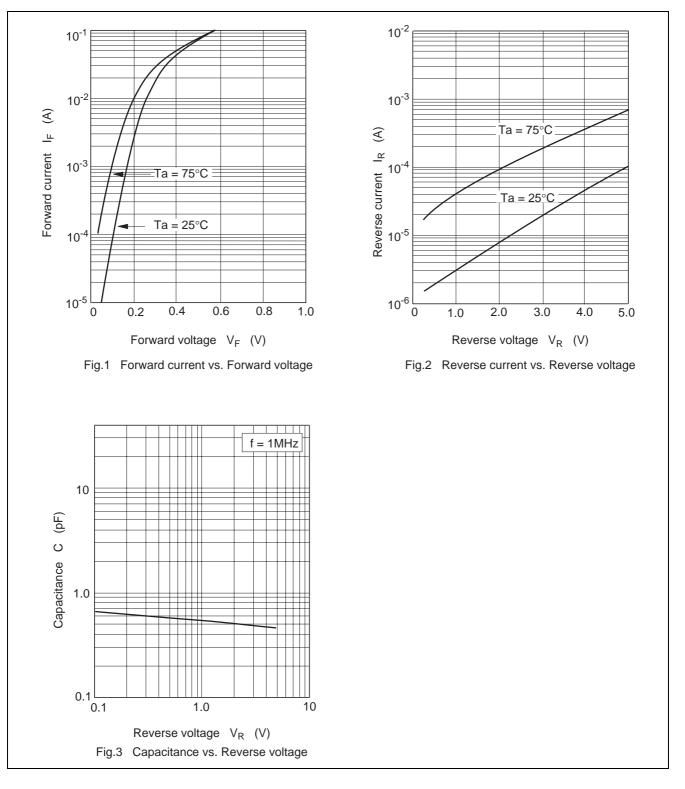
ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V _R	3	_	_	V	I _R = 1 mA
Reverse current	I _R	_	_	50	μA	V _R = 0.5 V
Forward current	I _F	35	_	_	mA	V _F = 0.5 V
Capacitance	С	_	_	0.85	pF	V _R = 0.5 V, f = 1 MHz
Capacitance deviation	ΔC	_	_	0.10	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capabilityme * ²	—	30	_	_	V	C = 200 pF, R = 0 Ω , Both forward and
						reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; $I_R>100~\mu A$ at V_R = 0.5 V

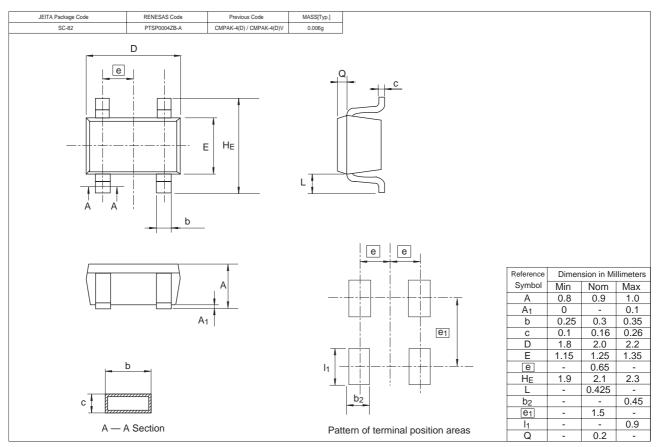


Main Characteristic





Package Dimensions





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